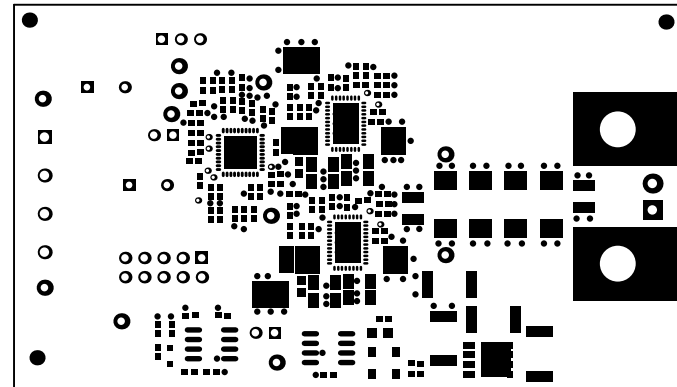
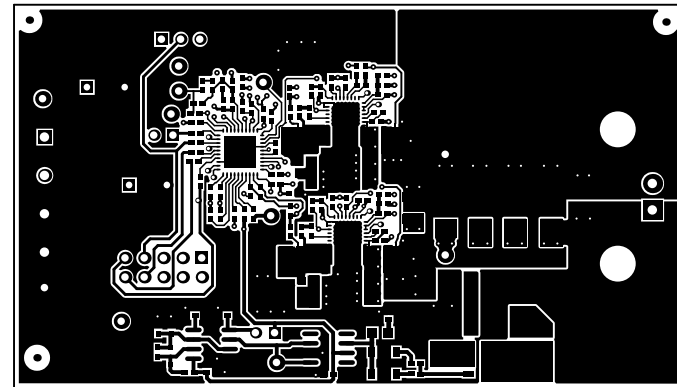


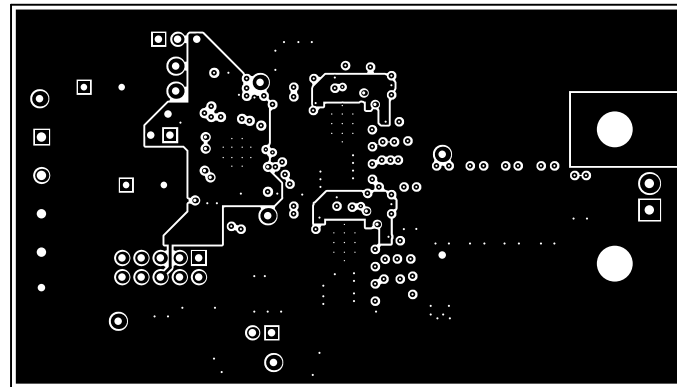
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP1196	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: PMP1196		
PLOT NAME = Top Overlay	GENERATED : 12/28/2015 2:00:11 PM	TEXAS INSTRUMENTS	



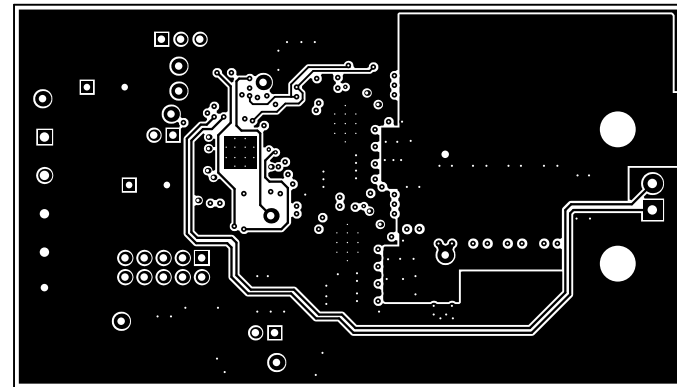
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11196	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: PMP11196		
PLOT NAME = Top Solder Mask	GENERATED : 12/28/2015 2:00:12 PM	TEXAS INSTRUMENTS	



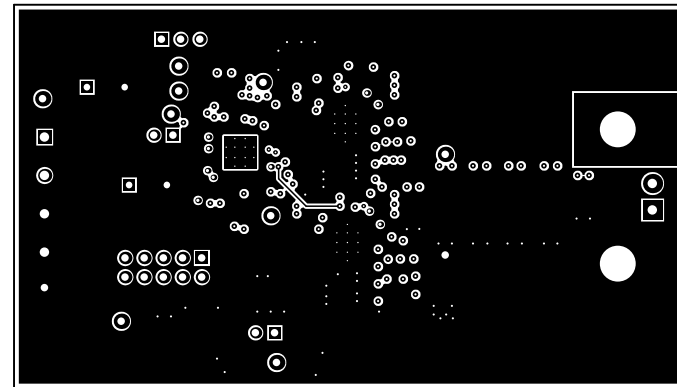
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11196	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: PMP11196		
PLOT NAME = Top Layer	GENERATED : 12/28/2015 2:00:13 PM	TEXAS INSTRUMENTS	



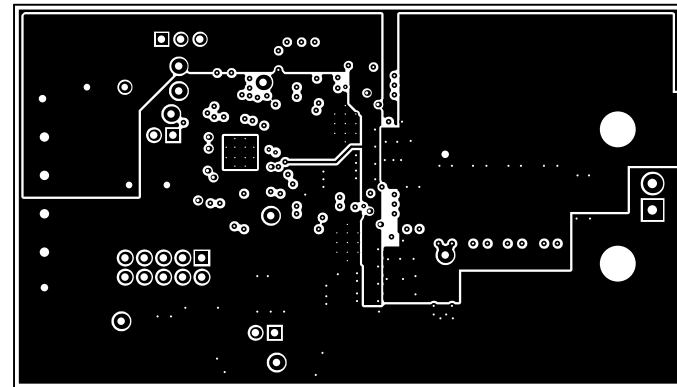
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11196	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP11196		
PLOT NAME = Signal Layer 1	GENERATED : 12/28/2015 2:00:14 PM	TEXAS INSTRUMENTS	



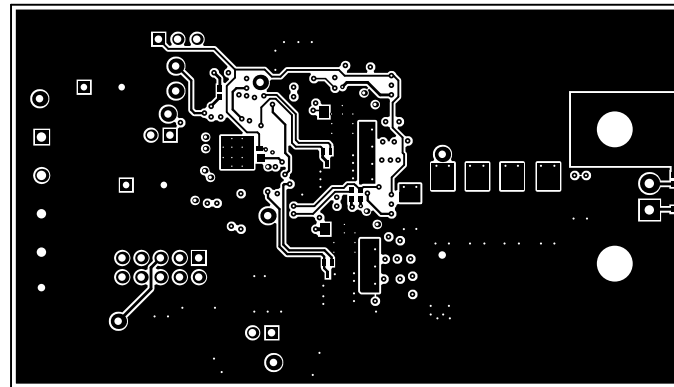
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11196	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP11196		
PLOT NAME = Signal Layer 2	GENERATED : 12/28/2015 2:00:15 PM	TEXAS INSTRUMENTS	



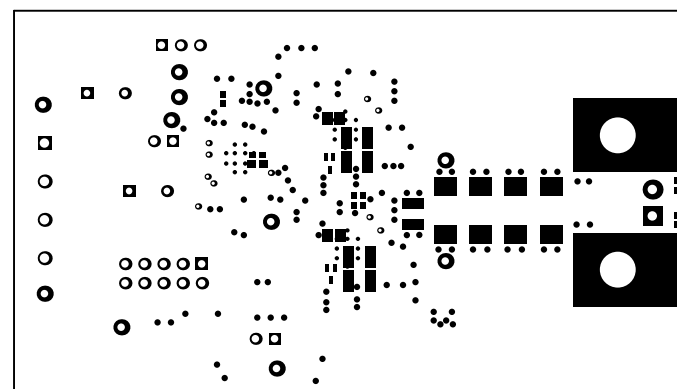
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11196	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP11196		
PLOT NAME = Signal Layer 3	GENERATED : 12/28/2015 2:00:16 PM	TEXAS INSTRUMENTS	



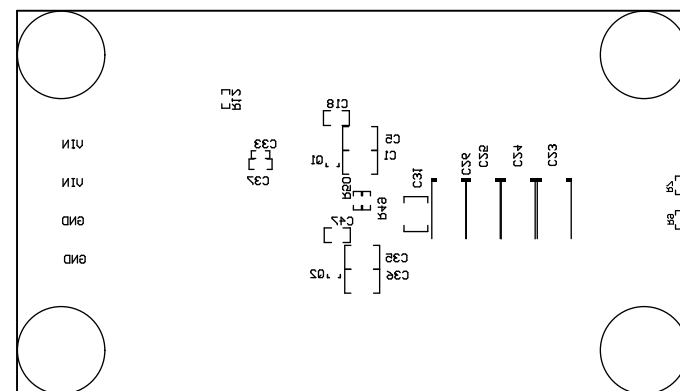
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11196	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP11196		
PLOT NAME = Signal Layer 4	GENERATED : 12/28/2015 2:00:17 PM	TEXAS INSTRUMENTS	



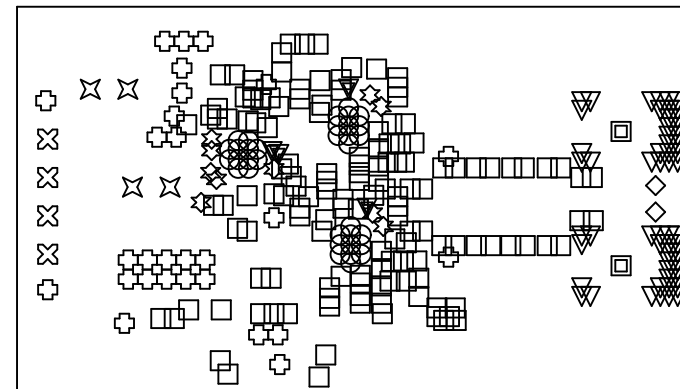
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11196	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: PMP11196		
PLOT NAME = Bottom Layer	GENERATED : 12/28/2015 2:00:18 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11196	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: PMP11196		
PLOT NAME = Bottom Solder Mask	GENERATED : 12/28/2015 2:00:19 PM	TEXAS INSTRUMENTS	

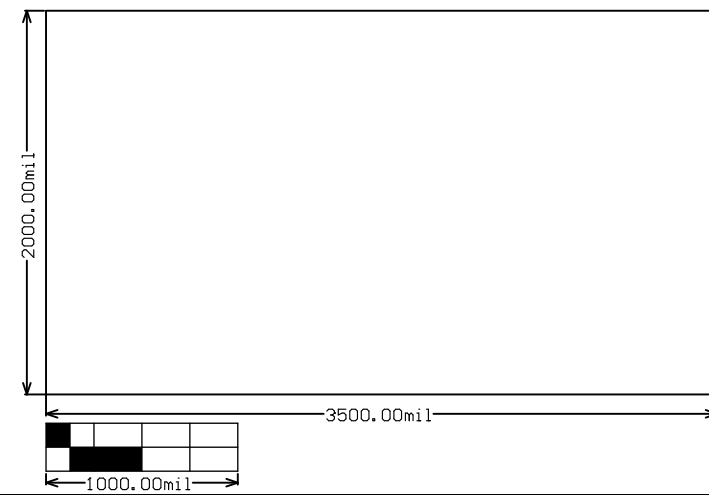


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11196	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: PMP11196		
PLOT NAME = Bottom Overlay	GENERATED : 12/28/2015 2:00:21 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
○	34	7.87mil (0.200mm)	PTH	Round
▼	4	10.00mil (0.254mm)	PTH	Round
□	142	12.00mil (0.305mm)	PTH	Round
▽	56	16.00mil (0.406mm)	PTH	Round
☆	10	17.72mil (0.450mm)	PTH	Round
✕	4	35.43mil (0.900mm)	PTH	Round
⊗	28	40.00mil (1.016mm)	PTH	Round
⊗	4	49.21mil (1.250mm)	PTH	Round
◇	2	50.00mil (1.270mm)	PTH	Round
■	2	188.00mil (4.775mm)	PTH	Round
	286 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11196	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: PMP11196		
PLOT NAME = Drill Drawing	GENERATED : 12/28/2015 2:00:22 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11196	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: PMP11196		
PLOT NAME = Board Dimensions	GENERATED : 12/28/2015 2:00:23 PM	TEXAS INSTRUMENTS	

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